

Title (en)

METHOD OF PROTECTING AN UNDERLYING WIRING LAYER DURING DUAL DAMASCENE PROCESSING

Title (de)

VERFAHREN ZUM SCHUTZ EINER UNTEREN KONTAKTSCHICHT WÄHREND DER HERSTELLUNG EINER DOPPELDAMASZEN-STRUKTUR

Title (fr)

PROCEDE PERMETTANT DE PROTEGER UNE COUCHE DE CABLAGE SOUS-JACENTE LORS D'UN PROCEDE DE DOUBLE DAMASQUINAGE

Publication

EP 1192656 A1 20020403 (EN)

Application

EP 00943434 A 20000605

Priority

- US 0040108 W 20000605
- US 34558699 A 19990630

Abstract (en)

[origin: WO0101480A1] A method of forming an interconnection including the steps of forming a sacrificial material (160) that comprises a physical property that is generally insensitive to a photoreaction in a via (150) through a dielectric material (130) to a masking material (120) over a conductive material (110). The method also includes forming a trench (180) over in the dielectric material over the via (150) and removing the sacrificial material (160) from the via.

IPC 1-7

H01L 21/768

IPC 8 full level

H01L 21/3205 (2006.01); **H01L 21/768** (2006.01); **H01L 23/52** (2006.01)

CPC (source: EP KR)

H01L 21/768 (2013.01 - KR); **H01L 21/76808** (2013.01 - EP); **H01L 21/76834** (2013.01 - EP)

Citation (search report)

See references of WO 0101480A1

Designated contracting state (EPC)

DE GB IE

DOCDB simple family (publication)

WO 0101480 A1 20010104; AU 5790800 A 20010131; EP 1192656 A1 20020403; HK 1042380 A1 20020809; IL 147301 A0 20020814; IL 147301 A 20060705; JP 2003528442 A 20030924; JP 4675534 B2 20110427; KR 100452418 B1 20041012; KR 20020020921 A 20020316; TW 531789 B 20030511

DOCDB simple family (application)

US 0040108 W 20000605; AU 5790800 A 20000605; EP 00943434 A 20000605; HK 02104146 A 20020531; IL 14730100 A 20000605; IL 14730101 A 20011225; JP 2001506606 A 20000605; KR 20017016608 A 20011224; TW 89112999 A 20000819